3-dim ensional distribution of spin-polarized current: application to (Cu/Co) pillar structures

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(D ated: January 12, 2022)

We present a form alism determ ining spin-polarized current and electrochem ical potential inside arbitrary electric circuit within di usive regime for parallel/antiparallel magnetic states. When arbitrary nano-structure is expressed by 3-dimensional (3D) electric circuit, we can determ ine 3D spin-polarized current and electrochem ical potential distributions inside it. We apply this technique to (Cu/Co) pillar structures, where pillar is term inated either by in nitely large Cu layer, or by Cu wire with identical cross-sectional area as pillar itself. We found that in nitely large Cu layers work as a strong spin-scatterers, increasing magnitude of spin-polarized current inside the pillar twice and reducing spin accumulation nearly to zero. As most experimentally studied pillar structures are term inated by such a in nitely large layers, we propose modi cation of standard Valet-Fert form alism to simply include in uence of such in nitely large layers.

PACS num bers: 75.75.+ a, 85.70 K h, 85.70 A y

I. IN TRODUCTION

Spin in jection, transport, and detection are key factors in the eld of magnetoelectronics. Especially, magnetization reversal using spin-polarized current is of great interest [1, 2, 3, 4, 5, 6, 7] due to its potential technologicalapplications such as MRAM [8], spin transistor [9] or spin battery [10].

To understand and optim ize spin-transport behavior in such devices, it is important to know a current distribution in it. Particularly for MRAM applications, we have to know spin-current magnitude and distribution to optim ize the current density necessary for spin-injection induced magnetization reversal. Variety of formalisms calculating magnetoelectronic transport in one dimension (ID) even for non-collinear magnetization has been proposed [11, 12, 13, 14, 15].

However, up to now, the spatial (3D) calculation of the spin-polarized current have been missing. To obtain spatial distribution of spin-polarized current (and spin accumulation) in a given structure, we express such a structure as a 3D circuit of spin-dependent-resistorelements (SDRE), wherein the propagation is regarded as 1D problem [11, 16].

R esistor circuit network has been already used in [17] to simulate current lines in metal/insulator multilayers. However, in this case, they did not use spin-polarized current. Ichim ura et al. [18] have calculated 2D distribution of spin polarized current for Co/Al lateral spin valve structure. They did not use the electric circuit, but directly solved Poison equation by means of nite element method.

This article is organized as follows: Sections II and IIA present a matrix approach to calculate 1D di usive propagation of spin-polarized current and potential in the single SDRE.Section IIB shows how this form alism can be applied to a simple multilayer structure. This approach is just compact matrix rewriting the 1D Valet-Fert (VF) form alism [11]. Section III explains how to solve general electric circuit and Section IIIA tells how to divide nanostructure into circuit of SDREs. Finally, in Section IV we apply our calculations to $(Cu/Co)^2$, and $(Cu/Co)^3$ pillar structures, where cross-sectional areas of the rst and last layers are assumed either the same as the pillar, or in nitely large. We show how the presence of such in nitely large layers in uence currents and spin accumulation pro les. Finally SectionV shows how to modify VF form alism to describe in uence of the innitely large layers.

II. DIFFUSIVE TRANSPORT REGIME

In the di usive transport regime, equations deriving the spatial distribution of electrochem ical potential "=# and spin-polarized current density $j_{"=\#}$ inside ferro or non-m agnetic m etals are [11, 16, 19, 20]

$$r^{2}(\ _{\#}) = \frac{\ _{\#}}{2};$$
 (1)

$$j_{"=\#} = \frac{"_{=\#}}{e} r_{"=\#};$$
 (2)

where is spin- ip di usion length, $_{=\#} = (1)^{=2}$ conductivities for up and down channels, respectively and e the electron charge assumed to be e = 1 in this article.

O urm odel is based on the circuit of SDRE, consisting of layers and interfaces (Fig.1). We rst express response of a single layer. When Eqs. (1) (2) are solved in 1D, the profess of " and " (hereafter denoted as "=#) inside

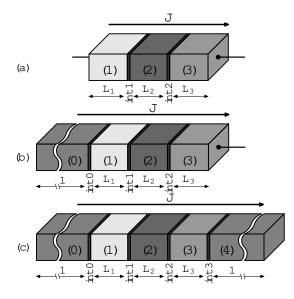


FIG. 1: A general form of (a) close-end SDRE (b) openend SDRE (c) classical multilayer structure having both ends open-ended. The arrow shows positive both structure and current direction. In all cases, SDRE has three layers, M = 3.

a given material along x-axis is given by [11, 16]

"=#
$$(x + L) = \sim (x) + \frac{j_{ch}e}{L} \quad c(x) = \exp[L =]$$

 $d(x) = \exp[L =];$ (3)

where $j_{ch} = j_{*} + j_{\#}$ is charge current density and positive current direction is towards positive x-direction. Energies c(x) and d(x) are amplitudes of exponential dum p-ing of "=# and the energy $\sim(x)$ is the asymptotic electrochem ical potential equivalent to weighted average of electrochem ical potentials $\sim = ("" + \#) = .$ The energies \sim , c and d will be determ ined later from boundary conditions.

The relation between $_{"=\#}$, $j_{"=\#}$ and \sim , c, d used in Eqs. (2) and (3) can be expressed in a compact matrix form

$$2 \ , 3 \ 2 \ , - 0 \ 3 \ 2 \ , 3 \ 3 \ 2 \ , 3 \ - 0 \ - 0 \ 3 \ 2 \ , 3 \ 3 \ - 0 \ -$$

where $J_{"=\#} = S j_{"=\#}$ is up/down spin-polarized current with cross-section area S of a given layer, $J_{ch} = J_{"} + J_{\#}$ is a charge current owing through layer. The scaling factor u which has no physical meaning, is introduced to adjust units of new ly de ned H and F vectors. For num erical calculations, value of u should adjust order of "=# and uJ"=#. W hen expressing any measurable quantities (e.g. "=#, J"=#, resitances), they obviously do not depend on u. The left side of Eq. (4) (H -vector) contains variables, which are conserved across interfaces or electric nodes. On the other hand, the right side of Eq. (4) (F -vector) contains variables, which are used to calculate propagation of the $J_{"=\#}$ and "=# through layers Eq. (3)]. Hence, the dynam ic D -m atrix relates coe cients at the boundary to coe cients for propagation. This approach is wellknown in the optics of an isotropic m edia [21, 22].

P ropagation of F -vector through layer with the thickness (\length") L is expressed by a propagation P-m atrix $\mathbb{E}q.(3)$]

Hence, the relation between $H = ["; "; uJ"; uJ_{#}]$ at both ends of the layer is expressed as

$$H_{x} = DPD^{-1}H_{x+L} = KH_{x+L}$$
: (6)

${\tt A}$. Interface resistivity and shunting interface resistance

In the previous Section, we have expressed response of one layer in hom ogeneous material. Here, we describe the interfacial properties including (i) interface resistance [11] AR $_{"=\#} = 2AR^2$ (1) and (ii) interfacial spin- ip scattering, described by a shunting resistance AR_s, \shortcutting" up and down channels at the interface. The response of interface can be expressed by K_{int} matrix

$$H_{x dx} = K_{int}H_{x+dx};$$
(7)

where x dx denotes for H -vector just below / above interface and K $_{\rm int}$ writes

$$K_{int} = \begin{cases} 2 & 0 & \frac{AR^{*}}{uS} & 0 \\ 6 & 0 & 1 & 0 & \frac{AR_{*}}{uS} & \frac{7}{uS} \\ \frac{uS}{AR_{s}} & \frac{uS}{AR_{s}} & 1 & 0 & \frac{5}{2} \\ \frac{uS}{AR_{s}} & \frac{uS}{AR_{s}} & 0 & 1 \end{cases}$$
(8)

Notice that alternative interfacial spin- ip scattering by $_{\rm I}$ -parameter was introduced in [23, 24] describing spin relaxation at the interfaces by a thin interfacial layer of spin- ip-length $_{\rm I}$ = $t_{\rm I}$ = $_{\rm I}$ where $t_{\rm I}$ is interfacial layer thickness. From comparison of K-matrices from Eqs.(6) and (8), AR $_{\rm s}$ = $4t_{\rm I}$ =($_{\rm I}$ $_{\rm I}^2$)sinh $_{\rm I}$ where $t_{\rm I}$ and $_{\rm I}$ are interfacial layer thickness and conductivity, respectively. W hen interfacial spin- ip scattering does not exist, then $R_{\rm s}=1$.

B. Sim ple multilayer structure

A lthough the form alism developed here is mainly to calculate $_{"=\#}$, $j_{"=\#}$ inside an electrical circuit, we shall

3

rst show how presented 4 4 m atrix algebra can be used to calculate electrical response of a multilayer structure Fig. 1 (c)].

The description for a single layer by matrix K in Eq. (6) gives relationship between "=# and J"=# at both ends of the layer. Hereafter, instead of continuity of spin-polarized current density $j_{"=\#}$ over interface, we consider continuity of spin-polarized current $J_{"=\#}$, to take into account variable cross-sectional area S of layers. The reasons and validity are discussed later in Section V. Obviously, when all layers has the same S, our form alism provides the same results as originalVF form alism [11].

The boundary conditions at interfaces are continuity of "=# and $J_{"=#}$, i.e. continuity of H -vector. Consequently, the response of whole multilayer structure can be written as [21, 22]

$$\mathbf{F}^{(0)} = \mathbf{M}^{(M+1)} \quad \mathbf{F}^{(M+1)}; \tag{9}$$

where

$$M^{(M+1)} = D^{(0)}] {}^{1} K^{(0)}_{int} K^{(1)} K^{(1)}_{int} :::$$
$$K^{(M-1)}_{int} K^{(M)} K^{(M)}_{int} D^{(M+1)}$$
(10)

where upper index in parenthesis denotes for interface or layer number, $M \;$ the number of layers.

Because materials (0) and (M + 1) are semi-in nite, "=# inside them must not exponentially increase. Hence, some exponential terms in Eq. (3) must vanish, namely $c^{(0)}$ 0, $d^{(M + 1)}$ 0. Hence, the vectors $F^{(0)}$ and $F^{(M + 1)}$ are limited to form

Now, Eq.(9) can be solved. Substituting Eq. (11) to Eq. (9), we found all unknowns in F $^{(M + 1)}$

$$c^{(M+1)} = M_{11} M_{12} U^{(M+1)} = M_{21} M_{22} U^{(M+1)} M_{24} J_{ch} + c^{(0)} U^{(12)}$$

where M $_{ij}$ are elements of M -m atrix. The value of $\sim^{(0)}$ can be arbitrary value, as it only adds a constant to the profiles of $_{"=\#}$. Other simplification of Eq. (12) follow from M $_{11}$ 1 and M $_{21}$ 0, in consequence of (i) for J_{ch} = 0 the terms $_{"=\#}$, \sim must be constant and equal to each other and (ii) for J_{ch} = 0, c^(M + 1) = 0. Then, solution of Eq. (12) can be written as

$$\sim^{(M + 1)} \sim^{(0)} = M_{14} + \frac{M_{12}M_{24}}{M_{22}} uJ_{ch}$$

$$c^{(M + 1)} = \frac{M_{24}}{M_{22}}uJ_{ch}:$$
(13)

Now, $\sim^{(M+1)}$ and $c^{(M+1)}$ are known and therefore the vector F $^{(M+1)}$ can be reconstructed from Eq. (11). Consequently, the pro-les of "=#, ~, J"=# etc. in the entire

structure can be determ ined by recursive applying stepby-step m atrix multiplications in Eq. (10)

F inally, resistivity of the multilayer structure (between rst and last interface) is R = $(\sqrt[\mathcal{M} + 1) ~ \sqrt[\mathcal{O}]) = J_{ch}$.

III. ELECTRIC CIRCUIT

As demonstrated in the previous Section, the M – matrix [de ned by Eq. \emptyset)] can characterize the entire multilayer structure where the same charge current J_{ch}

ows across all layers. In this Section, we extend the previous form alism to an electrical circuit (network) of SDREs, mutually connected at nodes. In general, the SDRE is composed of any sequence of materials (layers) and/or interfaces, as depicted on Fig.1. There are three types of SDRE, depending whether the length of SDRE is nite or in nite:

close-end SDRE [Fig.1(a)] has nite length and hence both ends of this SDRE are attached to nodes. Because the boundary condition at nodes are described by H -vectors, whole SDRE is described by K ^[b]-m atrix relating H -vectors at both ends of SDRE:

$$H^{[b](0)} = K^{[b]}H^{[b](M_{b})};$$
(14)

where, for later purpose, K^[b] can be rew ritten into four 2 2 submatrices

where b denotes a SDRE number in the circuit and M_b is the number of layers in b-th SDRE, $[D_{\mu}](M_{b})$ $[D_{\mu}](M_{b}); D_{\mu}](M_{b}); D_{\mu}](M_{b})$

$$K^{[b]} = K^{[b](1)} K^{[b](1)}_{int} ::: K^{[b](M_{b}-1)}_{int} K^{[b](M_{b})} : (16)$$

of layer and interface contributions

W hen SDRE contains only one layer (i.e. it consists of single metal), then [Eq. (6)] $K^{[b]} = K^{[b](1)}$ $D^{[b]}P^{[b]}D^{[b]}|^{1}$.

open-end SD RE [Fig1 (b)] has one end $\$ nite" and connected to the node. The other end is in nitely long and at its end the charge current $J_{ch}^{[b](0)}$, ow - ing into the b-th open-end SD RE, is applied. Because boundary conditions on node are described by H -vector and boundary conditions of the propagation into in nity by F -vector, the b-th open-end

SDRE is described by Z^[b]-matrix as

$$F^{[b](0)} = Z^{[b]} H^{[b](M_{b})};$$
(17)

where we have used convention that direction of SDRE and positive current direction goes from innite end of SDRE toward its nite end [Fig1(b)]. Analogous to Eqs. (10) and (16)

$$Z^{[b]} = \mathbb{D}^{[b](0)}]^{-1} K_{int}^{[b](0)} K^{[b](1)} K_{int}^{[b](1)} :::: K_{int}^{[b](M_{b}-1)} K^{[b](M_{b})} : (18)$$

W hen the SDRE contains no layer (i.e. it contains only single material continuous to in nity), then $Z^{[b]} = \mathbb{D}^{[b]} \mathbb{1}^{1}$.

multilayer structure [Fig. 1(c)] described in Sect. IIB may be understood as a special type of SDRE, having both ends open-ended.

In general, the electric circuit is assumed to have N nodes, C close-end SDRE and E open-end SDRE.

The boundary conditions valid for each node are determ ined by generalized K ircho 's law s:

$$[b_n]_{n;"=\#} = const_{n;"=\#} n;"=\#;$$
 (19)

$$\begin{array}{l} X^{n} \\ J^{(b_{n}]}_{n, "=\#} = 0; \\ b_{n} = 1 \end{array} (20)$$

i.e. the values of "=# has to be identical for all ends of SD RE connected to each node and sum of polarized currents J"=# entering each node has to be zero. Subscript n denotes for node number, n = 1 ::: N and $b_n = 1; :: B_n$ denotes the SD REs connected to the n-th node.

Hereafter, we use two -notation (i) $n_{;"=\#}$ relating "=# at the n-th node and (ii) ${}^{[b](0)}_{=\#}$, ${}^{[b](M_{b})}_{=\#}$ denoting "=# at start, end of the b-th SDRE, respectively. The

relation between these two -notations is given by connections between nodes and SDREs, i.e. by the topology of the electric circuit.

Following the previous discussion, the problem is how to treat large num ber of linear equations (14) (17) (19) (20) giving relations between "=# and $J_{"=#}$ on the nodes and between ends of SDREs. We do it by solving one large matrix expression,

$$Q \quad H = F; \qquad (21)$$

to which we apply all the previously mentioned rules. The H-vector contains __n;"=# for all nodes and also $uJ_{"=\#}^{[b](M_b)}$, b = 1:::C + E, at the end (i.e. at the M_b-side) of each SDRE.Hence, H-vector has 2 (C + E + N) elements.

The role of the Q-m atrix consists of three parts $\mathbb{E}q.(22)$:

- to relate "=#, J"=# at the \ nite" end of the openend SDREs and between boundary conditions of propagation towards in nity. This is provided by 2E linear equation, and hence this part occupies 2E rows in Q-m atrix.
- (2) to relate "=# between start and end of the closeend SDREs (2C linear equations).
- (3) to realize current conservation at each node (2N linear equations).

These contributions are studied in detail in following. In total, Q -m atrix has 2(C + E + N) rows, the same as length of H -vector. So Q is a square matrix.

An example of a circuit of SDREs is depicted in Figure 2. The circuit consist of N = 3 nodes, connected by SDRE.The circuit consists of C = 3 close-end SDRE and E = 2 open-end SDREs. Then, the resulting equation QH = F looks like:

	ź ^[1]	0	0	$\dot{z}_{J}^{[1]}$	0	0	0	0	3	2 3	1	2 2 F	[1](0)	3
6000	0	0	$\hat{z}^{_{0[5]}}$	0	0	0	0	$\hat{z}_{_{J}}^{_{0[5]}}$	1			6 F	0[5](0)	
000	1	κ ^[2]	0	0	K _J	0	0	0	4			6	0	7
യാത്ത	0	1	κ ^[3]	0	0	κ _{]3]}	0	0	7	§uJ ^{[1](M 1)} 7	=	200	0	7
000	1	0	κ ^[4]	0	0	0	K _J	0	_7	$uJ^{[2](M_2)}$		6	0 -	7
00004	0	K _J ^[2]	K _J [4]	1	K _{JJ}	0	K _{JJ}	0		$\begin{bmatrix} 6 \\ 0 \end{bmatrix} \begin{bmatrix} 3 \end{bmatrix} \begin{bmatrix} M \\ 3 \end{bmatrix} \begin{bmatrix} 3 \\ 7 \end{bmatrix} \begin{bmatrix} M \\ 3 \end{bmatrix} \begin{bmatrix} 3 \\ 7 \end{bmatrix} \begin{bmatrix} 2 \\ 7 \end{bmatrix} \begin{bmatrix} 3 \\ 7 \end{bmatrix} \begin{bmatrix} 1 \\ 1 $		200	0	
4	0	0	K _J [3]	0	1	K _{JJ}	0	0	5	° 4uJ ^{[4](M ₄)} 5 uJ ^{[5](M ₅)})	4	0 5	5
	0	0	0	0	0	1	1		1	uu			0	

(22)

where $[n; ; n; #]^T$ and 1, 0 denote 2 2 unitary, zero m atrix, respectively. Each row which is shown in Q =

matrix in Eq. (22) represents two rows (for up and down channel), so hereafter we call it \double-row".

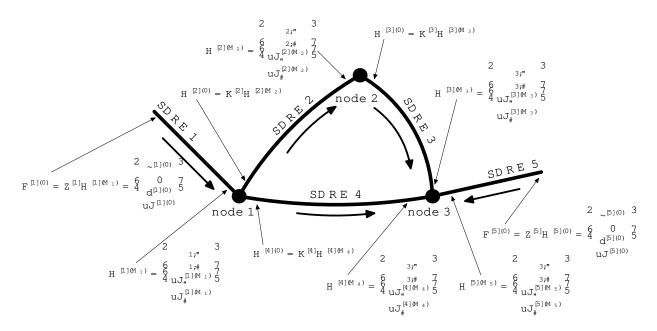


FIG. 2: The schem a of a circuit example, consisting of three node, two open-end SDRE and three close-end SDRE. The arrows parallel to SDRE shows the de ned direction of SDRE (and hence also positive current direction).

(ad 1) The role of the st part in the Q-matrix relates both ends of open-end SDRE, described by Eq. (17), F^{[b](0)} = Z^[b]H^{[b](M_b)}. However, we only know 2 variables out of 4 in vector F^{[b](0)} = $[\sim^{[b](0)}; c^{[b](0)}; d^{[b](0)}; u J_{ch}^{[b](0)}]^{T}$. We know charge current $J_{ch}^{[b](0)}$ entering b-th SDRE and that $c^{[b](0)} = 0$, because "=# must not exponentially increase towards in nity Eq.(11)]. Hence, taking from Z^[b] matrix Eq.(17)] only rows corresponding with known value in F^{[b](0)}, we get

$$\mathbf{F}^{(\mathbf{b})(0)} = \begin{array}{c} 2 & 3_{(\mathbf{b})(\mathbf{M}_{\mathbf{b}})} \\ \mathbf{E}^{(\mathbf{b})(0)} &= \begin{array}{c} 2 & 2_{1} & 2_{2} & 2_{23} & 2_{24} \\ 3 & 2_{1} & 2_{22} & 2_{23} & 2_{24} \\ 2 & 4_{1} & 2_{42} & 2_{43} & 2_{44} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{b}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \\ \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \end{array} \\ \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \end{array} \\ & \begin{array}{c} \mathbf{u}_{\mathbf{ch}} \end{array} \\ \\ &$$

In the case of the last open-end SDRE connected to the structure (in our example SDRE number $b^0 = 5$), the situation is slightly di erent. In the vector $F^{[b^0](0)} = [\sim^{[b^0](0)}; c^{[b^0](0)}; d^{[b^0](0)}; uJ_{ch}^{[b^0](0)}]^T$ (a) we have to set a value of $\sim^{[b^0](0)}$, which sets an absolute value of all "=# and ~ inside circuit to an arbitrary value and (b) getting a charge current $J_{ch}^{[b^0](0)}$ would be redundant as a sum of all charge currents entering circuit has to be zero. Hence, the last double-row in the rst part of the Q-m atrix (sec-

ond double-row in Eq. (22)) looks like

$$\mathbf{F}^{0[b^{0}](0)} = \begin{bmatrix} 2 & 3 & \mathbf{p}^{0} \\ \mathbf{F}^{0[b^{0}](0)} & \mathbf{F}^{0[b^{0}](0)} \\ 0 & = \begin{bmatrix} 2 & 11 & 2 & 12 & 2 & 13 & 2 & 14 \\ 2 & 11 & 2 & 12 & 2 & 13 & 2 & 14 \\ \mathbf{Z}^{21} & \mathbf{Z}^{22} & \mathbf{Z}^{23} & \mathbf{Z}^{24} & \mathbf{A}^{24} \mathbf{U}^{24} \mathbf{$$

and is substituted to Q -m atrix analogous as Eq. (23).

(ad 2) The second part in the Q-matrix gives relation between ${}^{[b](0)}_{"=\#}$ at the start of the b-th close-end SDRE and ${}^{[b](M_{b})}_{"=\#}$, $J^{[b](M_{b})}_{"=\#}$ at the end of b-th SDRE. This relation is given by the rst double row taken from Eq. (15). It is substituted into Q in the form $0 = {}^{[b](0)} + K {}^{[b](M_{b})} + uK {}^{[b]}_{T} J {}^{[b](M_{b})}$.

(ad 3) The last part in Q-m atrix describes the current conservation at each node, described by K ircho's law Eq. (20). As speci ed, H-vector contains only values of current at the end of each SD RE, $J_{n=\#}^{[b](M_b)}$. Hence, if the b-th SD RE starts at the n-th node (as No. 2 and 4 SD REs at the node 1), then the current is expressed by the second double-row in Eq. (15), from ${}^{[b](M_b)}_{n=\#}$, $J_{n=\#}^{[b](M_b)}$ as $uJ^{[b](0)} = K_J^{[b]}(M_b) + uK_{JJ}^{[b]}J^{[b](M_b)}$. For example, in case of node n = 1, the current conservation is $J_{n=\#}^{[1](M_1)} + J_{n=\#}^{[2](0)} + J_{n=\#}^{[4](0)} = 0$, which is substituted to Q-m atrix to the 6-th double-row as $J^{[1](M_1)} + K_J^{[2]}(2](M_2) + uK_{JJ}^{[2]}J^{[2](M_2)} + K_J^{[4]}(4](M_4) + uK_{JJ}J^{[4](M_4)} = 0$.

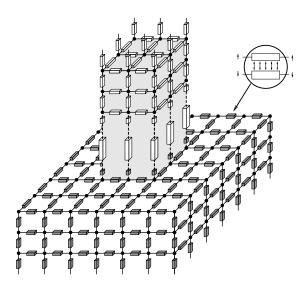


FIG.3: An example of dividing nanostructure into 3D circuit of SDRE.Each wire represents a \bus" of channel-up and channel-down. The inset remark that each SDRE consists of resistivity for channel-up, for channel-down and a spinip-scattering resistance between both channels. The large resistors denotes for interface resistivity [Eq. (8)].

A lthough the construction of the Q-matrix as presented here may be tedious, it is rather direct to establish its construction num erically. When the equation QH = F is solved, values of $"_{=\#}$, $J_{"=\#}$ for each SDRE are directly written in H-vector; their proles can be determined by step-by step applying multiplication in Eqs.(14) (16) and (17) (18).

A. Construction of 3D electric circuit

In the previous Section we have derived the form alism to calculate $J_{*=\#}$ and $*_{=\#}$ in arbitrary electric circuit. In this Section, we explain, how to describe the whole nanostructure as a circuit of SDREs, as sketched in Fig. 3.

Each part of the nanostructure is divided into 3D rectangular grid, the circuit nodes positions being x_i , y_j , z_k . Then, a given SD RE, for example in the x-direction, has length $L_i = (x_{i-1} + x_i)=2$ and cross-sectional area $S_{jk} = y_j z_k$. Due to this treatment, the grid does not need to be equally spaced, but just rectangular.

At the interface between two di erent materials, e.g. A and B (see Fig. 3), SDRE is described by $K_{A \mid B}$ matrix consisting of three contributions $K_{A \mid B} =$ $K_{A \mid int}K_{int}K_{int \mid B}$ [Eq. (16)]. The $K_{A \mid int}$ is contribution from grid point (node) inside A material to the interface with (SDRE is now along the z-direction) $L_k =$ $z_{int} = z_k = 1$ and $S_{ij} = x_i y_j$. K_{int} is the interface resistivity matrix given by Eq.(8). $K_{int! B}$ is contribution from the interface to the node in B material having $L = z_k = z_{int}$ and $S_{ij} = x_i y_j$.

The electrical circuit network as described above describes correctly charge current. How ever, inside 3D (2D)

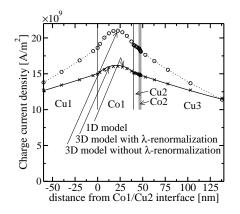


FIG.4: j_{sp} through $(C u/C o)^2$ structure with constant cross-sectional area S calculated by 1D model (line), by our 3D model with () and without () -renorm alization.

SD RE circuit the volum e of m etal in all resistors is three (two) times larger than in reality. In such a case, the spin-polarized current would have larger dumping, as it would di use into larger volume. To correct this, it is necessary to calculate 1D propagation of "=# in each SD RE by slightly modi ed Eq. 1)

where f is a dimension of the SDRE circuit. In other words, when a given nanostructure is described by 3D (2D) electrical circuit, the should be increased by a factor $\overline{3}$ ($\overline{2}$). This -norm alization should not be applied for open-end SDREs, as their contribution is correctly described by 1D propagation.

The advantage of this -norm alization is shown in Figure 4, where j_{sp} through (Cu/Co)² structure (described and studied in detail in the next Section) is compared between 1D model (full line), and our 3D model without -norm alization () and with -norm alization (). We can see that with (without) -norm alization, the agreement between 1D and 3D model is about 1% (30%). The same is valid for spin-accumulation = "#, where calculation without -norm alization leads to 30% sm aller

B. Surface scattering

In this Section, we describe how to incorporate surface scattering to the presented form alism .

Surface scattering can be described by a shunting resistance R_s shortcutting up and down channels for a nodes situated just close to the wire surface. R_s has value $R_{s,m} = AR_s = S_n$, AR_s being surface scattering resistivity and S_n being surface area corresponding to the n-th node. W hen surface scattering is not presented, then obviously $R_{s,m}$ = inf. Surface scattering can be described

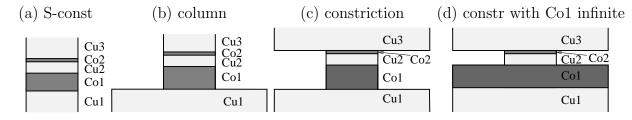


FIG. 5: Sketches of studied type structures. (a) S-constant (in nitely long nanow ire with constant cross-section area S), (b) column (in nitely long pillar deposited on in nitely large Cul layers) and (c) constriction (both Cu3 cover and Cul bu er layers are in nitely large) (d) constriction with Col in nite layer.

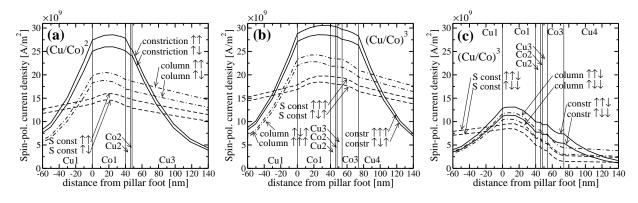


FIG.6: j_{sp} along center axis of the (a) $(Co/Cu)^2$ "", "# (b) $(Co/Cu)^3$ """, "#" (c) $(Co/Cu)^3$ ""#, "## for S-constant, column and constriction structure types [Fig.5].

by modi cation of Kircho law [Eq.20)]

$$\begin{array}{ccc} X & & & \\ & & J_{n}, "=\# & \\ & & & R_{s} \end{array} & \begin{array}{c} & & n, " & & n, \# \\ & & & R_{s} \end{array} = 0 :$$
 (26)

To incorporate this modi cation into Q -m atrix for the n-th node, we add G $_{\rm s}$ m atrix

$$G_{s} = \frac{1}{R_{s}} \frac{1}{1} \frac{1}{1} \frac{1}{1}$$
(27)

on the n-th double-column and n-th double-row in the last part of Q -m atrix which describes current conservation in each node. In our example given by Eq. (22) and Figure 2, to add R_s to n = 2 node, we place G_s to the 7-th double-row and 2-nd double-column into Q -m atrix.

IV. APPLICATION TO (Cu/Co) PILLAR STRUCTURE

In this Section we use the above developed form alism on $(Cu/Co)^2$ and $(Cu/Co)^3$ pillar structures. We will show how spin-polarized current density $j_{sp} = j_{*}$ and electrochem ical potential "=# vary di erently between when whole structure is a pillar or only a part of the structure is a pillar attached to an in nitely large continuous layer. In the literature, pillars term inated with in nitely large continuous layers are commonly used [2, 3, 4, 25, 26].

We have studied structures consisting of 2 and 3 Co layers, called $(Cu/Co)^2$, and $(Cu/Co)^3$ with dim ensions in nm Cu1/Co1(40)/Cu2(6)/Co2(2)/Cu3 and Cu1/Co1(40)/Cu2(6)/Co2(2)/Cu3(6)/Co3(20)/Cu4, respectively. The square-shaped pillar 100 nm in size begins with the Col/Cu2 interface. The considered structure types are de ned in Fig.5 as (a) cross-sectional area S constant, (b) column, (c) constriction and (d) constriction with in nite Col layer. In the following discussion, \constriction" corresponds to the case (c). The \in nite" hom ogeneous layers were approxim ated as a square pillar of 800 nm in size. The magnetization of Col layer is always xed as \up" ("), whereas magnetic orientations of other Co layers are varied. Note that in our di usive transport calculations, the magnetization orientation with respect to the structure (e.g. inplane or out-of-plane) do not play any role, but only mutual magnetization orientation (parallel or antiparallel) does play an important role. The charge current passing through structure is assumed to be $J_{ch} = 1 \text{ m A}$, equivalent to the averaged charge current density in the pillar $j_{ch} = 100 \quad 10^{\circ} \text{ A/m}^2$. The electrical properties of m aterials are of room tem perature [16, 27, 28]: electric conductivity $_{Cu} = 4.81 \quad 10^{\circ} \quad {}^{1}m \quad {}^{1}$, $_{Co} = 4.2 \quad 10^{\circ}$ ¹m ¹, spin-ip-lengths $_{Cu}$ = 350 nm , $_{Co}$ = 60 nm and Co spin bulk assymetry = 0:35. We assume no interface resistance and no interface and surface scattering. The SDRE grid size is 10 nm .

	j_{sp} [10 ⁹ A/m ²]	[m eV]	MR [8]
$(Cu/Co)^2$ "" S-constant (+)	14.85 [14.93]	-0.223 [-0.220]	0.483 [0.485]
$(Cu/Co)^2$ "" column ()	19.0 [19.8]	-0.267 [-0.276]	0.63 [0.66]
$(Cu/Co)^2$ "" constriction ()	29.4 [33.7]	-0.052 [-0.009]	1.01 [1.17]
(Cu/Co) ² "" constr, Col in nite	28.7 [23.3]	-0.050 [0.001]	1.43 [2.48]
$(Cu/Co)^3$ """ S-constant ()	19.51 [19.67]	-0.078 [-0.077]	0.444 [0.448]
(Cu/Co) ³ """ column (4)	23.6 [24.5]	-0.171 [-0.184]	0.55 [0.57]
$(Cu/Co)^3$ """ constriction (5)	31.0 [33.9]	-0.019 [-0.005]	0.74 [0.81]
$(Cu/Co)^3$ ""# S-constant ()	5.94 [5.93]	-0.442 [-0.438]	0.116 [0.115]
(Cu/Co) ³ ""# colum n (.)	8.08 [8.49]	-0.490 [-0.494]	0.162 [0.171]
$(Cu/Co)^3$ ""# constriction (/)	9.7 [10.5]	-0.458 [-0.456]	0.192 [0.210]

TABLE I: Values of j_{sp} , = " # at the position of free C o2 layer for $(C u/C o)^2$ and $(C u/C o)^3$ structures. M agnetoresistance ration (M R) is determined between rst and last C o/C u interface. All values are determined as averadge over whole pillar cross-section area. In square brackets we present values calculated from modi ed 1D VF form alism, which takes into account a variable cross-sectional area of the layers (Sect. V). Sym bols in parentheses denote structure notation in Fig. 11.

A. Current density in the structure

Figure 6 shows the pro le of jo along center axis of the structures: (a) (Cu/Co)² (b) (Cu/Co)³ with parallelCo1 and Co3 layers and (c) $(Cu/Co)^3$ with antiparallelCo1 and Co3 layers for S constant, column and constriction type structures. In all cases, j_{sp} for parallel C o1 and Col layer is larger than for antiparallel con guration. Furtherm ore, j_{sp} is enhanced at the position of free C o2 layer for the column and constriction types compared to the S constant type structure. For example, in the case of the constriction type structure with $(Cu/Co)^2$ "" con guration, j_{p} is enhanced by a factor of 1.75 and in the case of (Cu/Co)³ """ by 1.5. When only Cu bu er layer is in nite in size (colum n-type structure), jo at the position of C o2 layer is enhanced too, but not so strongly. Figure 6(c) shows that for $(Cu/Co)^3$ with antiparallel Col and Co3 layers, jsp is signi cantly reduced for all types of structures.

The origin of the j_{sp} enhancement is following: the pillar is attached to in nitely large Cu layer which provides large volume for spin-current to be scattered and so acting as a strong spin- ip-scatterer. Hence, in nitely large Cu layer works as a small shortcutting resistance between up and down channels. Consequently, short-cutting of up and down channels leads to an increase in j_{sp} . The increase of j_{sp} is related with increase of spin-polarization e ciency $p = j_{sp} (J_{ch}=S_{pillar})$, as charge current owing though pillar J_{h} is xed in all our calculations. Consequently, increase of p leads to decrease of critical switching current $J_{s;ch}$ which is necessary to reverse m agnetization direction of free layer.

As the constriction type structure is in the most com – mon use for Co/Cu pillar structures, the j_{sp} enhancement (i.e. $J_{s,ch}$ reduction) has been already widely used [4, 5] without being noticed. Similar elect can be realized by inserting a layer with small characteristic spin- ip resistance AR = = , such as Pt, Ag, Au, Ru above the last Co layer or bellow the rst Co layer. Such cover layers has been used [29, 30] since the rst pioneering experiment [3], but their contributions to the j_{sp} enhancem ent have been observed recently [30, 31, 32].

Figure 7 shows pro less of charge current $j_h = j_r + j_{\#}$ along the center axis of the $(Cu/Co)^3$ structure for S constant, column and constriction type structures. Obviously, for S constant structure, the j_{ch} is constant. In the case of in nite Cu term ination, j_p decreases approximately exponentially over the characteristic length of 50 nm. The same decay of j_{sp} is presented in Fig. 6 for in nitely large Cu layers.

In Table I, we sum marize averadged values of j_{sp} in the position of Co2 layer in all the types of studied structures. These j_{sp} values may di er from those presented in Fig. 6 due to lateral inhom ogenity of j_{sp} inside pillar, discussed in next Section. The largest averaged j_{sp} is obtained for $(Cu/Co)^3$ """ constriction structure $(31.0 \quad 10^9 \text{ A/m}^2)$ and $(Cu/Co)^2$ "" constriction structure

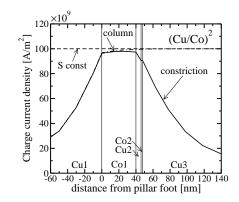


FIG. 7: j_{ch} along center axis of the $(C o/C u)^2$ structure for S-constant, colum n and constriction structure types Fig. 5].

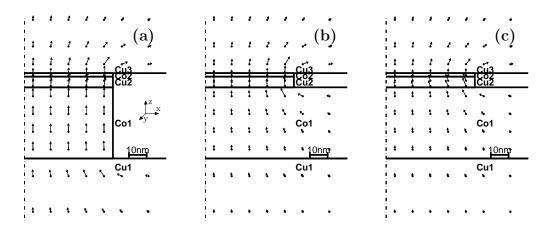


FIG.8: Spin polarized current in $(Cu/Co)^2$ construction-type structure (a) without in nitely large Col layer, "" (b) with in nitely large Col layer "" (c) as (b) but "#.

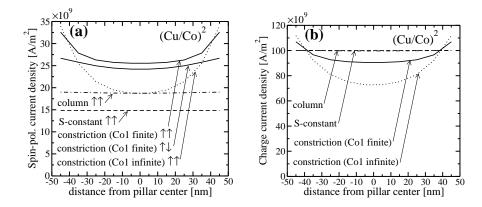


FIG.9: (a) j_{sp} and (b) j_{ch} in the middle of the Co2 layer inside $(Cu/Co)^2$ structures.

ture (29:4 10° A/m^2), providing j_{sp} enhancement by a factor 2 with respect to $(\text{Co/Cu})^2$ S-constant structure (14.85 10° A/m^2). This tendency is already explained in above paragraph.

B. Current inhom ogenity inside pillar

Figure 8 presents a map of spin-polarized current density j_{sp} inside (Cu/Co)² constriction type structure for (a) (b) parallel and (c) antiparallel magnetization con guration. The case (a) is a structure without in nitely large Col layer whereas (b) (c) with it. A map of j_{ch} is not presented here as it boks sim ilar to j_{sp} with "". The j_{sp} inside Co2 layers is more hom ogenous and ow swell perpendicular to the interfaces although in the surrounding Cu layers the j_{sp} can have rather large inclination and inhom ogenity. The j_{sp} tends to be more hom ogeneous when passing Co layer, causing that the j_{sp} in the adjacent Cu layers can have rather large in-plane com – ponents. This is remarkable in the case (c). Very sim ilar tendency is found for j_{ch} .

The above mentioned characteristics of j_{sp} are consequence of larger spin- ip resistance AR =

= of Co with respect to Cu, AR $_{;Co} = 14.3 \text{ fm}^2$, AR $_{;Cu} = 7.3 \text{ fm}^2$. It means that spin- ip is more likely to occur inside Cu than inside Co. In other words, Co is \harder" material than Cu for j_{sp} to penetrate into it. The above mentioned characteristics of j_{ch} are simply consequence of $_{Co}$ $_{Cu}$.

Figure 9 shows cross-sectional (in x-direction) pro les of (a) j_{sp} and (b) j_{ch} through pillar in the m iddle of the $C \circ 2$ layer for $(C u/C \circ)^2$ structure. Both j_{sp} and j_{ch} are inhom ogenous having m in im a at the structure center. This is due to inhom ogenous current in jection into the pillar from in nitely large layers. There is no j_p and j_{ch} inhom ogenity for S constant and nearly no inhom ogenity in case of column type structure as the j_{sp} and j_{ch} are hom ogenized by a C ol layer. For constriction type structure the inhom ogenity is 12% for "" and 5% for "#. Inhomogenity is de ned as (j_{max}) $\dot{j}_{m in}$)=($\dot{j}_{m ax}$ + $\dot{j}_{m in}$), where maximal, minimalvalue is taken from cross-sectional current distribution in Fig. 9. The inhom ogenity is reduced for "# due to di erent conductivities of up and down channel conductivities, leading to other current hom ogenization in Cu2 spacer layer. If Co1 layer is in nitly large, the inhom ogenity is increased to 10% and 29% for "" and "#, respectively. The j_{ch} inhom ogenity is 8% and

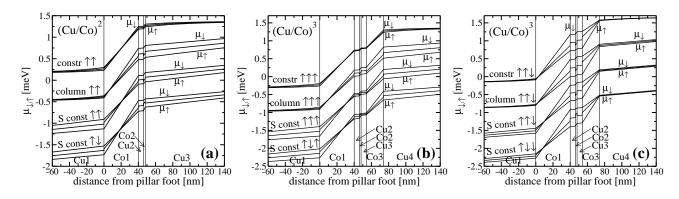


FIG.10: Electro-chem ical potential $_{=#}$ along center axis of the (a) $(Cu/Co)^2$ "", "# (b) $(Cu/Co)^3$ """, "#" and (c) $(Cu/Co)^3$ """, "#" for S constant, column and construction structure types [Fig.5].

20% for constriction type structure with and without innitely large C ol layer, respectively.

Here remains a question whether such a $j_{\rm sp}$ inhom ogenities make current magnetization reversal easier or not. A dventage of $j_{\rm sp}$ inhom ogeneity may be, that it locally enhanced $j_{\rm sp}$ near the pillar edge, wheas decreasing $j_{\rm sp}$ at the pillar center. As shown in Table I, the mean value of $j_{\rm sp}$ is about the same for $(C\,u/C\,o)^2$ constriction structure with and without in nitely large C of layer. How ever, in the second case, $j_{\rm sp}$ is much more inhom ogenous. This is not well presented in Fig. 9(a), we do not see the largest $j_{\rm sp}$ owing in the vicinity of the corners of the square pillars. D isadventage of $j_{\rm sp}$ inhom ogenity may be di erent magnitude of torgue exerted on magnetic spins of free C o2 layer. This may be particularly in portant in the case of high speed switching associated with magnetization precession.

C. Electrochem ical potential inside structure

Figure 10 presents pro les of ", $_{\#}$ and ~ (hereafter -pro les) along the center axis of the (a) (Cu/Co)² "", "# (b) (Cu/Co)³ """, "#" and (c) (Cu/Co)³ ""#, "##. S-constant structure is presented for both m agnetization directions of Co2 layers, although colum n and constriction types are presented only for " m agnetization of Co2 layer. In contrast to j_{sp} , inhom ogenity of spin accum ulation at the position of free Co2 layer is very sm all, m ostly bellow 1%. Table I presents a m ean value of for all types of the studied structures.

Figures 10 (a) (b) and (c) show that -pro les depend slightly on magnetization of free Co2 layer because t_{Co2} co. Figure 10 (a) exhibits suppression of in the vicinity of in nitely large Cu layer. The reason is exactly the same as discussed in Sec. IV A: the in nitely large Cu layer works as a strong spin-scatterer, causing a sm all spin- ip resistance (large scattering) between up and down channels. O bviously, such a shortcut reduces

This is contradictory to [30, 31, 32], where it is argued that presence of spin-scatterer increases spin acululation

inside pillar. It should be emphasized that presence of spin-scatterers increases $j_{\rm sp}~$ (and m agnetoresistance) in the pillar, but reduce ~ .

Table I shows that the largest is obtained for colum n type structure, by 20% larger than for S-constant type structure. The reason is as follow : when Cul is not in nitely large (S constant structure), changes its sign approximately in the middle of Collayer Fig. 10 (a) S constant]. W hen Cul is in nitely large, it acts as strong spin-scatterer and shortcuts up and down chanat Cu1/Co1 interface is nearly zero and nels. Hence, is obtained at the Col/Cu2 interface hence larger and inside Co2 layer Fig. 10(a) column]. But to realize this, it is necessary that up and down channels above free Co2 layer should not be shortcut m eaning that the cover layer has not to be in nite.

Figure 10 (b) shows that is reduced when Col and Co3 layers have parallel m agnetization con guration. Figure 10 (c) shows an increase in when Co1 and Co3 layers are antiparallel, enhancing by factor of 2 with respect to $(Cu/Co)^2$ S constant structure. In this case the types of structure are not so important as in $(Cu/Co)^2$ case, because at the position of Co2 free layer is \screened" by spin-scattering inside Co1 and Co3 layers.

Hence, there is e ectively no spin-accumulation in the case of a commonly used constriction type structure with two FM layers. It may explain why this contribution to magnetization reversal (predicted in [33]) was not observed in Co/Cu structure [25]. To obtain non-, it is necessary to use either 3 FM layer system zero with antiparallel con guration of rst and last FM layers, or to ensure that structure above free layer will not contain spin-scatterers. It can be reached when pillar structure above free layer (i) does not contain any strong spin-scatterer layers (as Au, Ag, Pt, Ru) and (ii) the cover layer does not contain large volum e of m etal. It m eans that pillar current drain should be realized by a long pillar or by a thin cover layer.

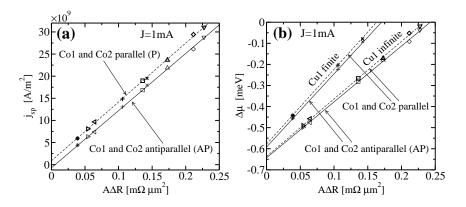


FIG.11: Dependence of (a) j_{sp} and (b) on A R for di errent studied (Cu/Co) structure, symbol notation in Tab I. Lines are the best linear ts, dashed line and bold symbols (full line and norm al symbols) denote parallel (antiparallel) Col and Co2 layers. Cul in nite m eans column and construction types, Cul nite m eans S constant type.

D. M agnetoresistance

Finally, we discuss in uence of type structure on m agnetoresistance ratio (M R), presented in the last column in Table I. The value of M R is determined as M R= ($\sim_{\text{m}} \sim_{\#}$)=($\sim_{\text{m}} + \sim_{\#}$), where ", # denotes m agnetization of free Co2 layer, $\sim_{\text{m}=\#} = \sim_{\text{last};\text{m}=\#} \sim_{\text{rst};\text{m}=\#}$, where $\sim_{\text{rst};\text{m}=\#}$ and $\sim_{\text{last};\text{m}=\#}$ are determined on Cu side of the rst and last Cu/Co interface, respectively.

The calculated value of M R in the case of $(Cu/Co)^2$ S-constant structure is 0.48%. However, in the case of $(Cu/Co)^2$ constriction type, it reachs 1.01% (enhancement by a factor of 2) and in the case of the constriction with in nite Col layer even 1.43% (enhancement by a factor of 3). The last value may be m isleading as this increase is mainly due to resistivity reduction of Col innite layer.

Table I shows MR is strongly a ected by the type structure, increasing with an increase of j_{sp} rather than

. This tendency may be observed also for $(C o/C u)^3$ layer, showing increase (decrease) in MR when Col and Co3 layers have parallel (antiparallel) magnetization conguration.

Figure 11 (a) shows dependance of j_{sp} on A R, where R = R_{*} R_#, where ", # m eans up, down m agnetization of Co2 layer, respectively. It shows that j_{sp} is proportional to R. This gure is analogous to the experimental dependence of critical switching current $J_{s,ch}$ as a function of R [30, 31, 32], where they found that $1=J_{s,ch}$ is proportional to R.

These graphs are analogous from following reasons: to switch magnetic layer we need to overcome the critical spin-polarized current density

$$j_{s;sp;0} = pJ_{s;ch} = S_{pillar};$$
(28)

where $J_{s;ch}$ is critical switching charge current and p is spin-polarized current injection e ciency. Because $j_{s;sp;0}$ and S_{pillar} are constant, so p $1=J_{s;ch}$. On the other hand, from our calculations, we can express p as $p = j_{sp} = (J_{ch} = S_{pillar})$, where J_{ch} is a xed charge current

ow ing to the structure; therefore p_{sp} . However, in our model, j_{sp} is slightly larger for Col and Co2 parallel con guration (Fig.6), although in [30, 31, 32], $1=J_{s;ch}$ is larger for antiparallel con guration, in agreem ent with the spin-transfer model [34]. Figure 11 (a) also provides an in portant consequence: when changing electric properties of surroundings of FM (xed)/spacer/FM (free) layers, an enhancem ent of j_{sp} in the position of free layer leads to enhancem ent of M R.

Figure 11 (b) shows dependence of on R.We can see that with increasing R, is reduced. Two different slopes correspond to two di erent \sources" acting as with di erent \hardness". The source hardness is determined by a presence or absence of scatterers bellow xed Col layer. Hard source is for constriction and column structure type, ie. when Cul is in-

nitely large. W eak one is for S constant structure type, i.e. when for Cul is not in nitely large. The explanation of this behavior has been already provided in previous Section IV C: when spin- ip scatterer is presented bellow xed Col layer, it vanishes on Cul/Col interface and hence provides harder source of . Figure 11 also shows that when changing surroundings of FM (xed)/spacer/FM (free) layers, an increase in at the position of free layer is related to a decrease of M R.

Remark, that for constriction type structure with Col layer in nitely large [case(d) in Fig.5], the \source" of becomes softer than for constriction type [case (c) in

Fig. 5].

V. EXPRESSION OF INFINITELY LARGE LAYERS BY 1D MODELS

As we have shown, the constriction type structures modify the prole of both $\frac{1}{2p}$ and $_{;\#}$ with respect to S constant types, which provides equivalent results to 1D VF form alism [11]. However, to describe $\frac{1}{2p}$ and $_{=\#}$ inside structure by 3D modelm ay be tedious procedure. That is why here we discuss brie y, how to modiled VF

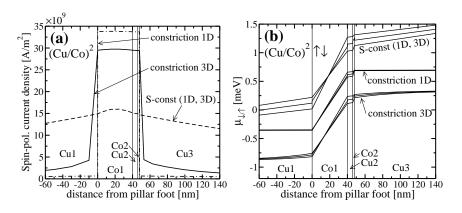


FIG. 12: (a) averaged value of spin-polarized current and (b) $_{*=\#}$ in the structure center calculated for constriction type structure with and without Col in nite layer in the $(Cu/Co)^2$ "# compared with 1D calculations taking into account in nite Cu layers. See Section V for detail.

model to take into account in nitely large layers.

W e propose, that each layer can have its own crosssectional area S_i. Then, instead of conserving spin polarized current density $j_{"=\#}$ in the 1D form alism , we propose to conserve spin polarized current $J_{"=#}$. A ctually, we have used this boundary condition already in Section IIB. This boundary condition is justi ed when (i) thickness of the layer Li is thick enough compared to the change of pillar diam eter between neighboring lay $a_{i,1} j \leq L_i$, where a_i aj< Li, jai ers, ja_{i+1} S_i, so that current has enough space to spread to di erent cross-sectional area S_i (ii) pillar diam eter a_i is sm aller than spin-ip length . It can be shown that if S_i ! inf, then j_{"=#}, _{"=#}, MR etc. converge. So, it is not im portant, how large value S_i is used to describe in nitely large layers.

Figure 12 shows j_{sp} and $~_{=\#}$ calculated by 3D m odels in the case of constriction type structure. These data are compared with 1D m odels with and without expanding the term inating C u layers, called \1D constriction" and \S constant", respectively.

3D constriction is described by 1D constriction (S constant) model with precision of 15% (50%) for j_{sp} and 40% (80%) for [Fig. 12 (a) (b)]. The agreement between for constriction type structure is quite poor, because at this con guration is very small. In the case of larger than the above case, the agreement is about 10%.

This 1D m odel has been used to calculate j_{sp} , and M R in the position of free C o2 layer for all types of studied structures. The results are presented in Table I in square brackets; we can see rather good agreement in all cases. An exception is the case of constriction type structure with in nitely large C o1 layer, as in this case the condition (ii) is not full led.

VI. CONCLUSION

W e have developed form alism which allow sto calculate spin-polarized current j_{sp} , and electrochem ical potential "=# inside arbitrary electric circuit, consisting of ferroornon-m agneticm etallic SD RE elements as well as interface and surface resistivities. The form alism is limited to the parallel/antiparallelm agnetic orientation in di usive regim e.

To calculate spatial distribution of $"_{=\#}$, $j_{"=\#}$ inside nanostructure, we divide the structure into an 1D, 2D or 3D electric circuit network of SDRE elements which is successively solved. When division is carried out as described in Section IIIA, the renormalization of spin-

ip length has to be perform ed.

This form alism is applied to $(Cu/Co)^2$ and $(Cu/Co)^3$, pillar structures, where pillar cross-sectional area of starting/term inating layers were assumed to be either in-

nitely large (column type, constriction type) or they have the same cross-sectional area as pillar (S const types).

Inside the pillar surrounded by in nitely large layers, the j_{sp} , j_{ch} can be inhomogeneous. Maximal inhom ogeneity is found to be 29% and 20% in the case of innitely large Col layer. On the other hand, pro le of

is found m ore hom ogeneous, with found m aximum inhom ogeneity of 2%. Such j_{sp} inhom ogeneities m ay locally enhance the value of j_{sp} , but they m ay disturb the m agnetization reversal associated with spin precession. Due to _{co} _{cu}, AR _{;co} >> AR _{;cu}, both j_{ch} and j_{sp} ow rather perpendicular to the Co layers and furtherm ore the presence of Co layer m akes j_{sp} , j_{ch} m ore hom ogeneous.

W hen pillar is term inated by in nitely large layers, they serve as spin-scatterers, shortcutting up and down channels and hence modifying proles of and $\frac{1}{20}$.

W hen such a spin-scatterers (but it is also valid for di erent spin-scatterers, as layers of Au, Ag, Pt, Ru, etc.) are introduced bellow \ xed" Col layer, they m ake source \harder". W hen they are placed above free Co2 layer, they shortcut up and down channels, reducing nearly to zero, and hence enhancing j_{so} .

Consequently, to get maximum j_{sp} in the case of $(Cu/Co)^2$ at the position of \free" Co2 layer, it is important to introduce spin-scatterers both bellow xed Col layer and above free C o2 layer. To get m axim um , 辻 is in portant to introduce spin-scatterer bellow xed C ol layer, but reduce spin-scattering above Co2 free layer, latter one can be realized by reducing volum e of m aterial above C o2 layer, for example current drain can be thin long nanowire or cover layer with very thin thickness. As most of experimentally studied $(Cu/Co)^2$ structures have in nitely large layers at both ends, inside them is nearly zero.

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For $(C u/C o)^3$ system, maximum j_{sp} () is for parallel (antiparallel) magnetization of rst, last Co layer. W hen applying above described optimizations, j_{sp} and can be further enhanced.

Furtherm ore, in agreem ent with experimental results [30, 31, 32] we found that j_{sp} is linearly proportional to $R = R_{\#} - R_{*}$ (and hence M R is increased when increasing j_{sp} at the position of free C o2 layer). Furtherm ore, dependence of (R) is also linear, but is reduced when increasing R (when increasing M R).

Finally, we propose simple modi cation of 1D Valet-Fert formalism [11], to incorporate spin-scattering induced by in nitely large layers attached to pillar.

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